

Sipchem LD 2023 EO

Low Density Polyethylene Resin

Product description: Sipchem LD 2023 EO is a Low Density Polyethylene resin, manufactured by IPC an affiliate of Sipchem in The Kingdom of Saudi Arabia using an Exxon-Mobil high-pressure tubular process. LD 2023 EO is designed to offer a good balance of optical and mechanical properties.

Applications: Blend Partner, Cast Film, Compounding, Foam, Food Packaging, Form Fill and Seal Packaging, Freezer Film, Lamination Film, Light Duty Shrink Film, Liners, Mail Bag, Produce Bags, Shoppers, Textile Packaging, Tough Medium Sized Molding.

Additives: Thermal Stabiliser: 400 ppm Antiblock: No Slip: No

Properties	Typical Value	Unit	Test Method
Melt Index (190°C / 2.16 kg)	2.0	g/10 min	ASTM D1238
Density	0.923	g/cm ³	ASTM D1505
Melting Point	110	°C	ASTM D3418
Tensile Strength at Yield MD	11	MPa	ASTM D882
Tensile Strength at Yield TD	11	MPa	ASTM D882
Tensile Strength at Break MD	25	MPa	ASTM D882
Tensile Strength at Break TD	22	MPa	ASTM D882
Elongation at Break MD	330	%	ASTM D882
Elongation at Break TD	550	%	ASTM D882
Secant Modulus MD – 1% Secant	210	MPa	ASTM D882
Secant Modulus TD – 1% Secant	230	MPa	ASTM D882
Drop Dart Impact	80	g	ASTM D1709A
Elmendorf Tear Strength MD	150	g	ASTM D1922
Elmendorf Tear Strength TD	120	g	ASTM D1922
Gloss (45°C)	63	g	ASTM D2457
Haze	6.1	%	ASTM D1003

1. These are typical properties: these are not to be construed as specifications.
2. This product is not intended for use in medical applications and should not be used in any such applications.
3. Contact your Sipchem Representative for potential food contact application compliance.

Compliance & Product Stewardship Department

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Disclaimer

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